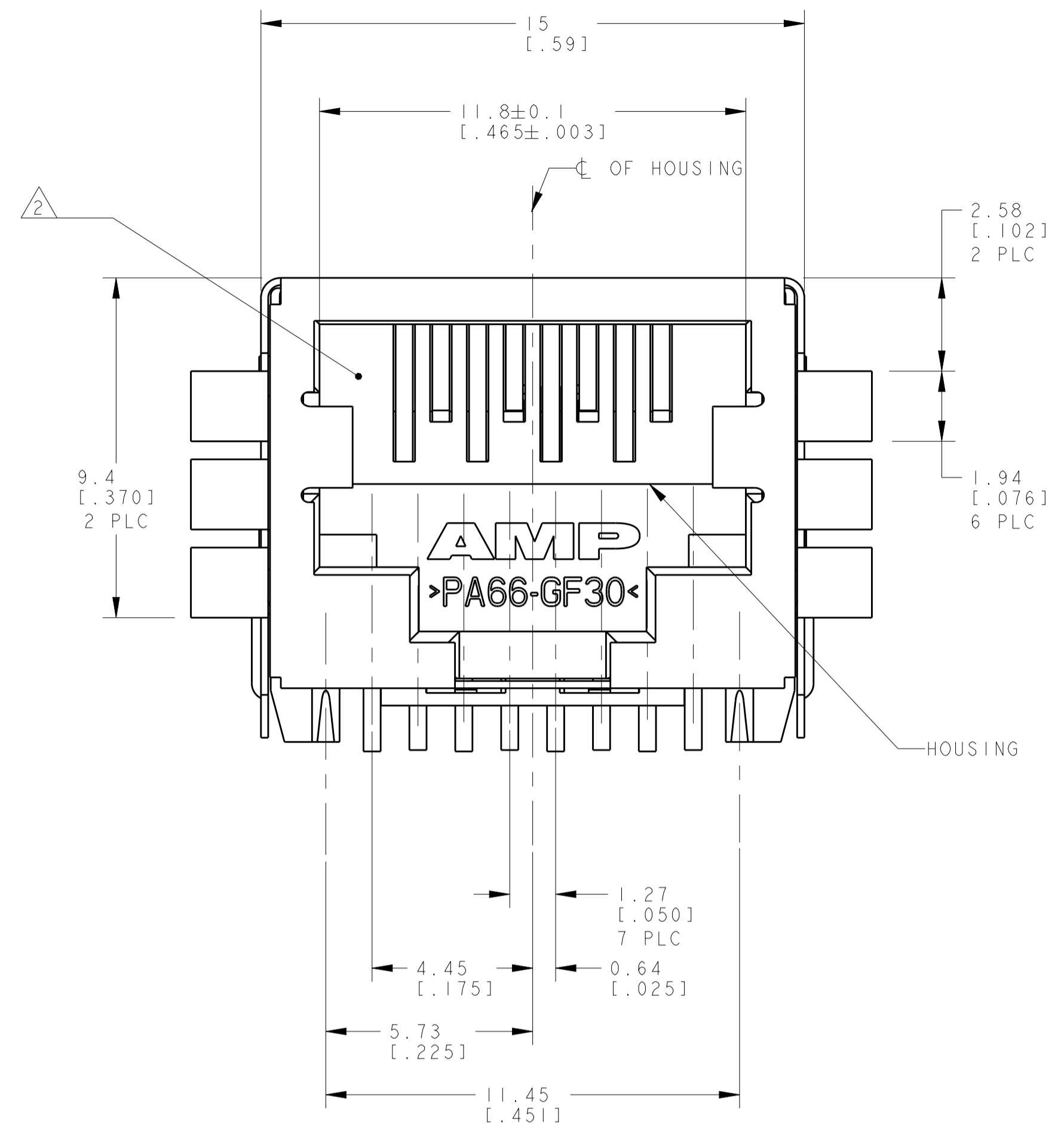
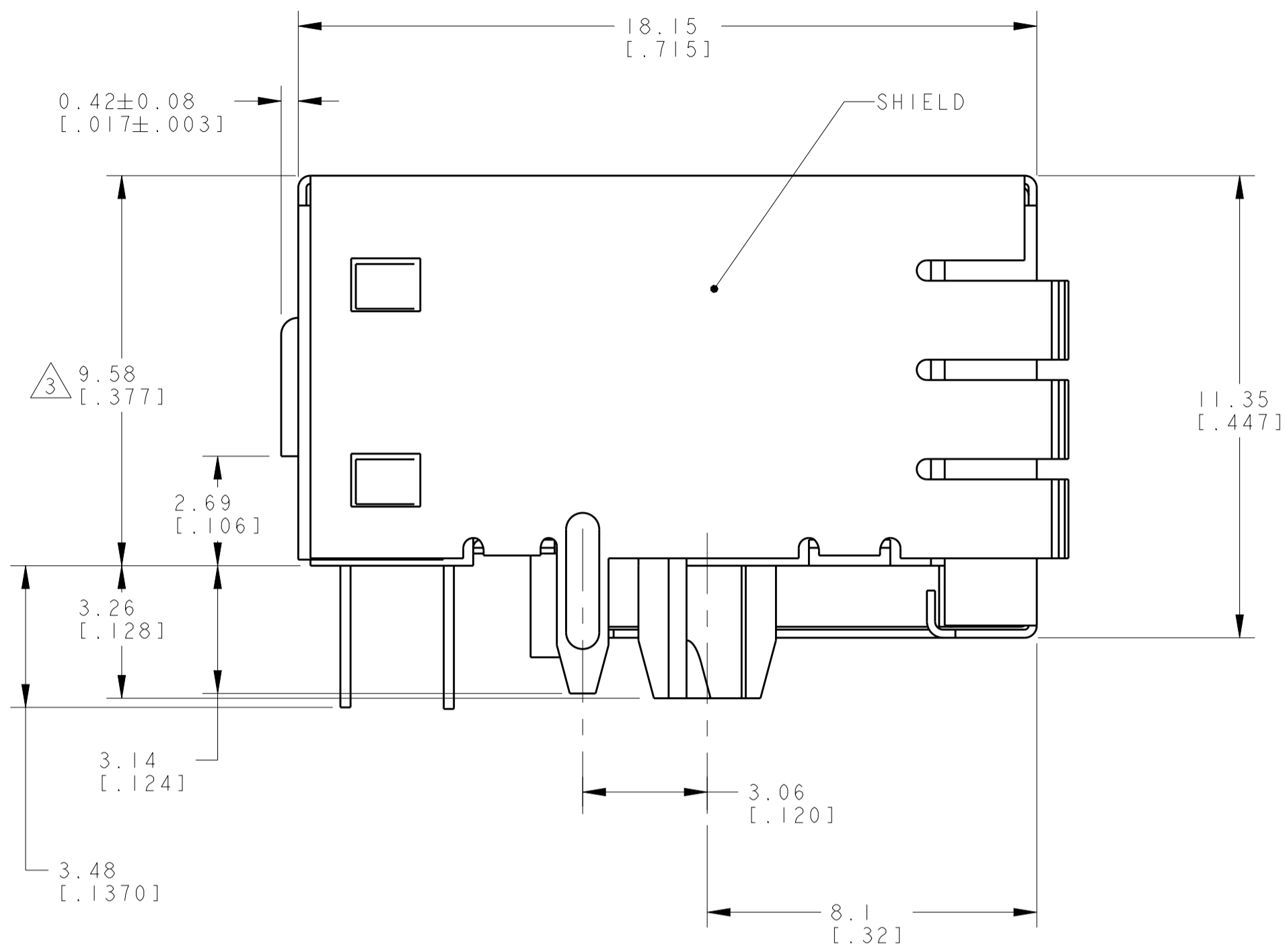
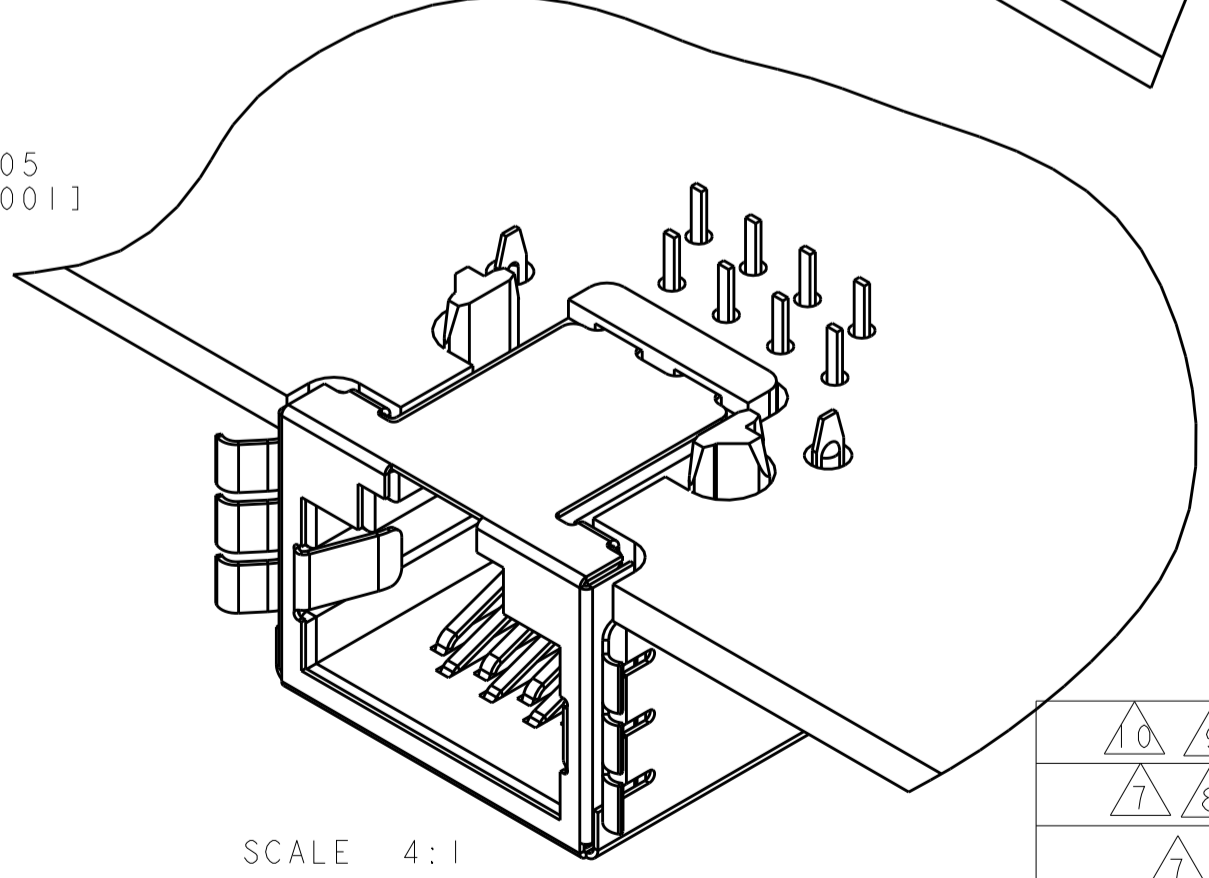
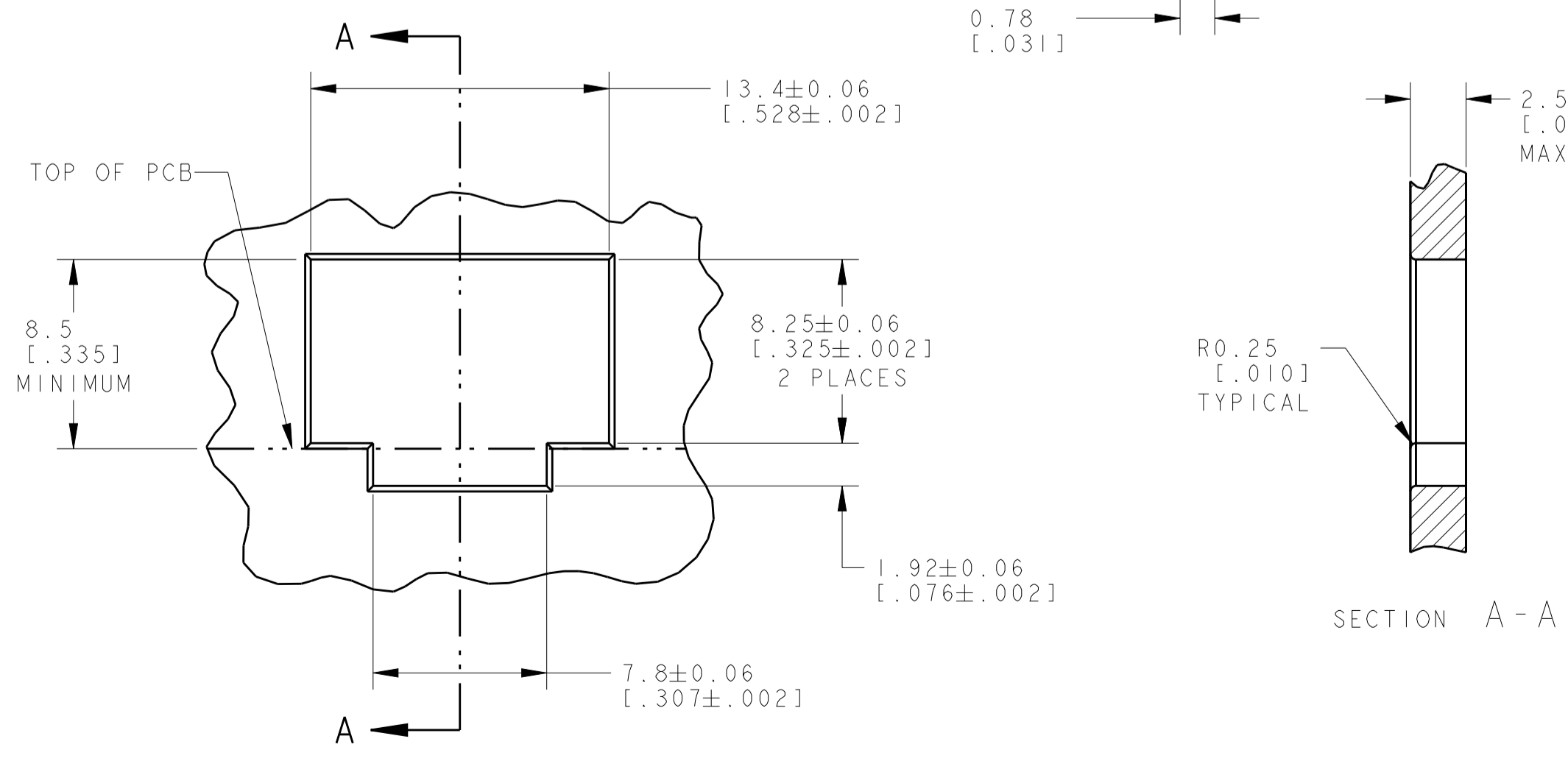
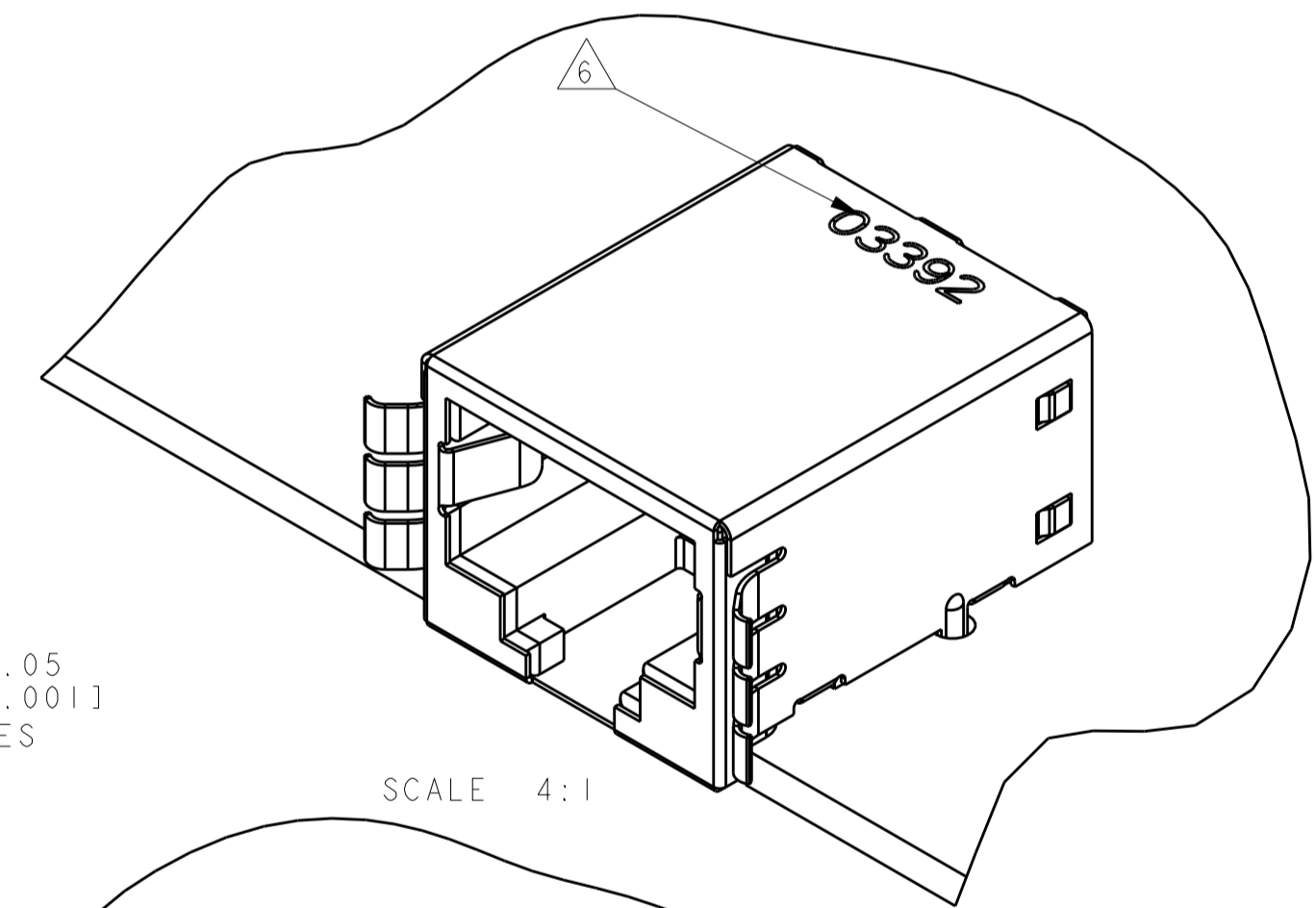
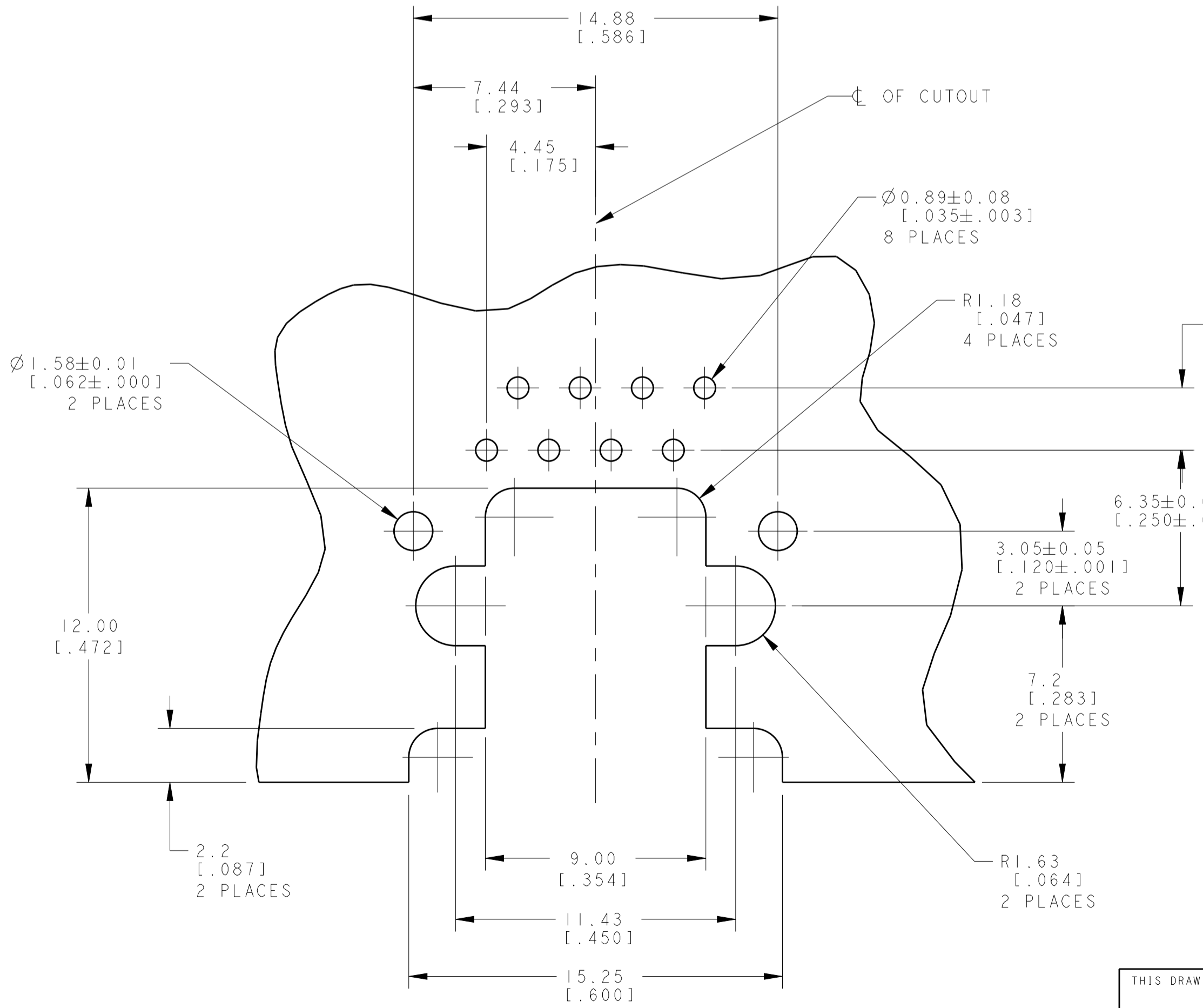
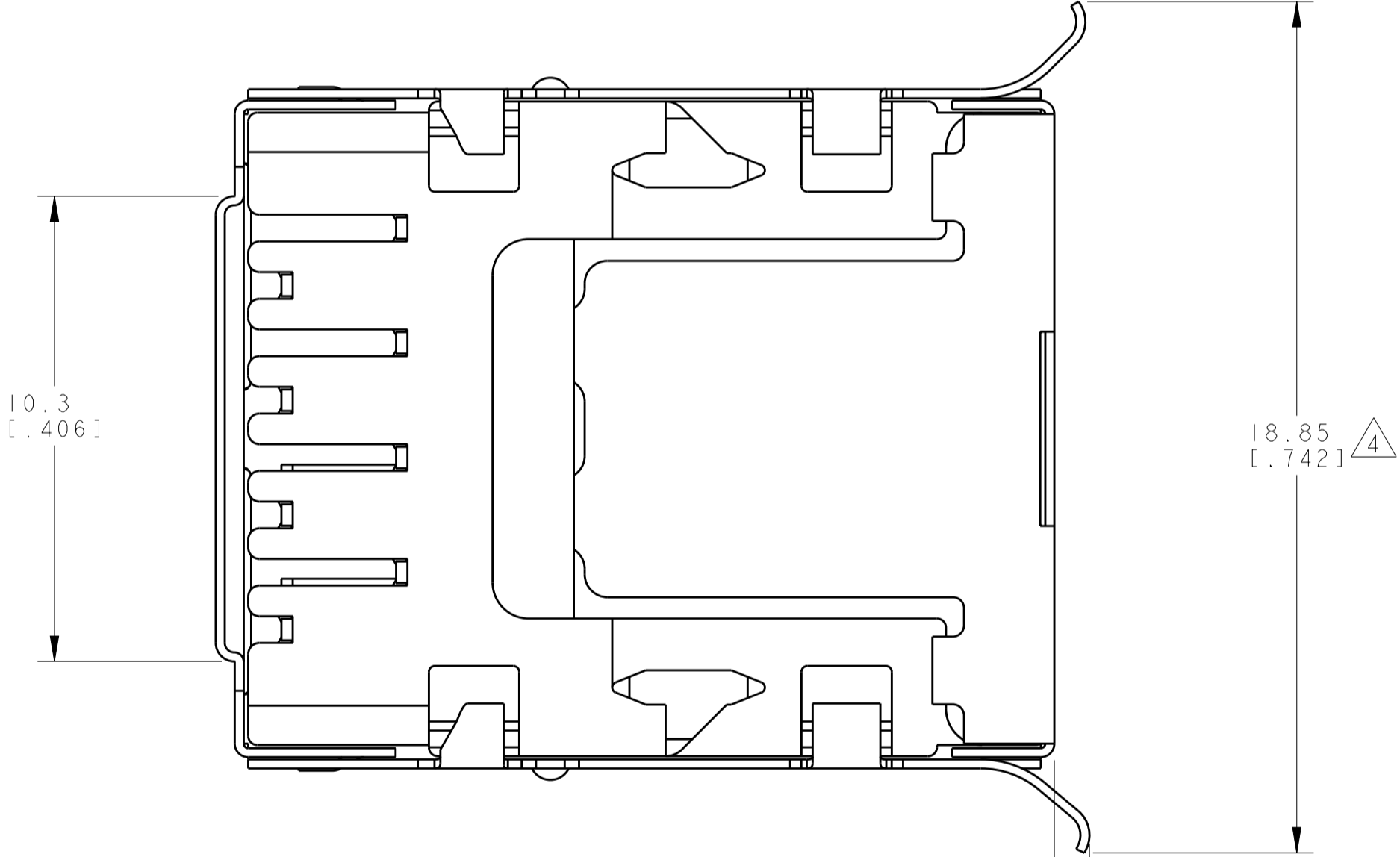


LOC	DIST	REV	DATE	BY	APPV
AA	22	T	24APR2015	LL	SH



- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25 [.010] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [.000150] MINIMUM THICK BRIGHT TIN-LEAD IN SOLDER AREA, 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.1 [.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [.000079-.000157] THICK TIN OVER 1.27µm [.000050] MIN THICK NICKEL.
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 THIS DIMENSION REPRESENTS THE TOTAL HEIGHT OF THE CONNECTOR FROM THE TOP OF THE PC BOARD.
- 4 THIS DIMENSION HAS A MAXIMUM VALUE OF 20.50 [.807] WHEN JACK IS INSTALLED BEHIND PANEL.
- 5. PACKAGED 66 ASSEMBLIES PER PVC TRAY, 396 PER BOX.
- 6 MANUFACTURING DATE CODE: ORIENTED AND LOCATED APPROXIMATELY AS SHOWN. LASER PRINTING. TEXT HEIGHT APPROXIMATELY 2MM. FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR NEXT 2 DIGITS = MANUFACTURING WORK WEEK LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1
- 7 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0, TERMINALS - 0.25 [.010] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA, 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.1 [.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 2.0-4.0µm [.000079-.000157] THICK TIN OVER 1.27µm [.000050] MIN THICK NICKEL.
- 8 PACKED WITH TAPE AND REEL PACKAGE.
- 9 MATERIAL: SHIELD - 0.1 [.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27µm [.000050] MIN THICK NICKEL, PCB GROUND TABS DIPPED WITH 2.03µm [.000080] MIN TIN. OTHER COMPONENT: AS SAME AS 7.
- 10. PACKED WITH DRY PACKING.



10	9	1116062-4
7	8	1116062-3
7		1116062-2
		1116062-1

OBsolete

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: J. AHERON 11NOV98	TE Connectivity
DIMENSIONS: mm [INCHES]		CHK: D. KEMPKA 11NOV98	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: D. KEMPKA 11NOV98	NAME: MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, 10mm PRODUCT SPEC: 108-1163 APPLICATION SPEC: 114-2048
0 PLC ±	1 PLC ±	WEIGHT: 3.49 grams	
2 PLC ±	3 PLC ±	CUSTOMER DRAWING	RESTRICTED TO
4 PLC ±	ANGLES ±	SCALE: 8:1	SHEET: 1 OF 1
MATERIAL: SEE P/N TABLE		PART NUMBER: 1116062-4	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)